LNJ210C6ARA

Surface Mounting Chip LED

SV (Side View) -Case Type

Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit	
Power dissipation	P _D	60	mW	
Forward current	I _F	20	mA	
Pulse forward current *	I _{FP}	60	mA	
Reverse voltage	V _R	3	V	
Operating ambient temperature	T _{opr}	-25 to +80	°C	
Storage temperature	T _{stg}	-30 to +85	°C	

Lighting Color

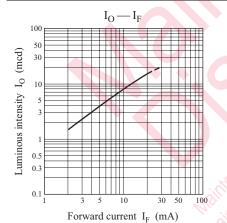
• Red

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

Electro-Optical Characteristics $T_a = 25^{\circ}C$

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Parameter	Symbol		Conditions	Min	Тур	Max	Unit
Luminous intensity	Io	$I_F = 10 \text{ mA}$		2.6	8.0	P	mcd
Reverse current	I _R	$V_R = 3 V$			1000	100	μΑ
Forward voltage	V _F	$I_F = 10 \text{ mA}$		(00°, 8°	1.72	2.5	V
Peak emission wavelength	λ_P	$I_{\rm F} = 10 {\rm mA}$	illes and	din	660		nm
Spectral half band width	Δλ	$I_F = 10 \text{ mA}$	in Oni		20		nm

 $I_F - V_F$



Relative luminous intensity

 $\lambda_{\rm P}$

60

80 60 40

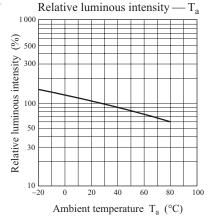
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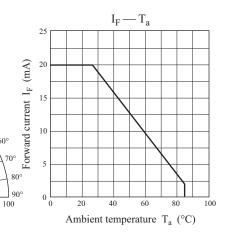
90°

800 100

Directive characteristics

30





600

700

Peak emission wavelength $\lambda_P~(nm)$

100

80

60

20

0 500

Relative luminous intensity (%)

0 20 40

Relative luminous intensity (%)

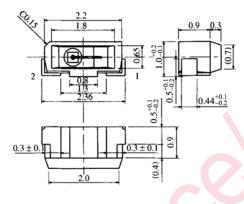
60 80

Panasonic

LNJ210C6ARA

Package (Unit: mm)

LLDFSR2J1000



• Pin name

1: Cathode

2: Anode

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